

**REMARKS**

The foregoing amendments are presented to remove the multiple dependencies of the claims in order to reduce the PTO filing fee.

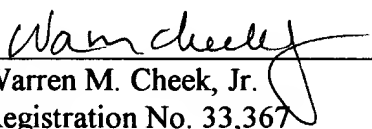
Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached pages are captioned "**Version with markings to show changes made**".

Favorable action on the merits is solicited.

Respectfully submitted,

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What is claimed is:

1. A punch or die for compressing granules to prepare tablets where basis material is a high-silicon steel.

5        2. The punch or die according to claim 1, wherein the surface of the basis material is subjected to a carburization treatment.

3. <sup>(Amended)</sup> The punch or die according to claim 1 ~~or 2~~, wherein it is applied to a punch (1, 2) or die (3) used for a tablet machine for the preparation of tablets containing corrosive substances or adhesive substances.

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4. The punch or die according to claim 3, wherein the corrosive substance is an acidic substance.

5. The punch or die according to claim 3, wherein the adhesive substance(s) is/are one or more substance(s) selected from a group consisting of adhesive pharmacologically active substance, adhesive low-melting substance and adhesive excipient.

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6. The punch or die according to claim 5, wherein the adhesive low-melting substance is resulted due to a depression of melting point.

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7. <sup>(Amended)</sup> A tablet machine which is characterized in being equipped with the punch or the die <sup>according to</sup> ~~mentioned in~~ claim 1 ~~or 2~~.

8. A method for manufacturing tablets, characterized in that, the tablet machine mentioned in claim 7 is used during compression of granules.

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9. The method according to claim 8, wherein the tablets contain corrosive substances or adhesive substances.

10. The manufacturing method according to claim 9, wherein

the corrosive substance is an acidic substance.

11. The manufacturing method according to claim 9, wherein the adhesive substance(s) is/are one or more substance(s) selected from a group consisting of adhesive pharmacologically active substance, adhesive low-melting substance and adhesive excipient.

12. The manufacturing method according to claim 11, wherein the adhesive low-melting substance is resulted due to a depression of melting point.

10 13. <sup>(Amended)</sup> Tablets which are manufactured according to the manufacturing method ~~mentioned in any one of the claims 8 to 12.~~ according to Claim 8